

ABSTRACT OF THE DISCLOSURE

An electronic device includes: a substrate on which an interconnect pattern is formed; a chip component having a first surface on which an electrode is formed and a
5 second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate; an insulating section formed of a resin and provided adjacent to the chip component; and an interconnect which is formed to extend from above the electrode, over the insulating section and to above the interconnect pattern.

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